

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S85	948	(polish or polishing or cmp or chemical adj mechanical adj polishing) and pad and (passivat\$6 or dielectric or inter adj layer or interlayer) and via and (tab or tape adj automated adj bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/19 15:09
S86	778	S85 and ((@ad<"20020627") or (@rlad<"20020627"))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/19 15:21
S87	10	(protect\$4 near8 tape) near8 adhesive near8 passivation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/19 15:23
S88	52	(bond or bonding) same tape same passivation same adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/19 15:27
S89	4469	((438/106) or (438/459)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/19 15:27

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Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	6764	((438/106) or (438/113) or (438/114) or (438/118) or (438/459)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/20 10:57
L2	703	(wafer or substrate) near8 (singulat\$4 or separat\$4 or dicing) same (adhesive) same tape same (street or (scribe near line) or cut or mark or marked or marking or indentation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 10:58
L13	110	1 and 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 10:58
L14	77	13 and ((@ad<"20020627") or (@rlad<"20020627"))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 11:36
L15	7	(wafer or substrate) near8 passivation near10 (pad or bond\$4) same tape same adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 11:11
L16	43	(wafer or substrate) same passivation same (pad or bond\$4) same tape same adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 11:12
L17	36	16 not 15	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 11:13
L18	821007	MATSUSHITA.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 11:14
L19	2	(bonding near pad) same (buffer near coat) same passivation same adhesive same tape	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 11:15

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L20	1496	(polish\$4 near4 ((rear near surface) or bottom) near8 (wafer or substrate))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 11:15
L21	28	18 and 20	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 11:16
L22	74923	Seo.in. or Matsuda.in. or Minamide.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 11:18
L23	7	20 and 22	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 11:19
L24	12	(bond\$4 with tape with adhesive with passivation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 11:20
L25	56	prevent\$4 with adhesive with pad with periphery	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 11:29
L26	77	adhesive near8 (contact\$4 or connect\$4) near8 passivation with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 11:30
L27	11	1 and 26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 11:32

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L28	277	(438/114).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/20 11:33
L29	47	(adhesive with passivation with tape)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 11:33
L30	0	28 and 29	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 11:33
L31	191	28 and ((@ad<"20020627") or (@rlad<"20020627"))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 13:44
L32	230	(438/413).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/20 13:40
L33	1608	(438/118).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/20 13:40
L34	6	(tape or (protective near layer) or protection) with adhesive with passivation with (peripheral or periphery or edge)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 13:43
L35	16831	(tape or (protective near layer) or protection) with adhesive with (peripheral or periphery or edge)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 13:44

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L36	947	(tape or (protective near layer) or protection) with adhesive with (peripheral or periphery or edge) with (substrate or wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 13:44
L37	15	33 and 36	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 13:44
L38	12	37 and ((@ad<"20020627") or (@rlad<"20020627"))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 13:53
L39	3516	(438/106).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/20 13:52
L40	172	39 and (tape or protection or protected or protecting) and (adhesive or sealant) and (passivation or passivating or passivated)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 13:57
L41	122	40 and ((@ad<"20020627") or (@rlad<"20020627"))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 13:57
L42	989	(438/459).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/20 13:57
L43	50	42 and (tape or protection or protected or protecting) and (adhesive or sealant) and (passivation or passivating or passivated)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/20 13:58

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L44	2	("6097087").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/20 13:58
L45	13	("5155302" "5206585" "5434357" "5440240" "5477160" "5593927" "5674785" "5678301" "5739585" "5770889" "5773322" "5783865" "5789278").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/20 13:58
L46	112	("6097087").URPN.	USPAT	OR	ON	2006/07/20 13:59